

ABSTRACT OF THE DISCLOSURE

The present invention is a chip for use in a voice communication device. The chip provides for both bone conduction sensing and air conduction sensing. The chip includes a bone conduction sensing pattern disposed within the chip and a microphone sensing pattern disposed within the chip. In addition, the chip can optionally include an integrated circuit portion interconnected to the bone conduction sensing pattern and the microphone sensing pattern. The pattern can be of a piezoelectric polymer, the patterns overlaying the substrate. Preferably, the bone conduction sensing pattern and the microphone sensing pattern are placed on opposite ends of the chip.

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